# **SPECIFICATION**

**PART NO. : OEL9M0065-Y-E** 



This specification may be changed without any notice in order to improve performance or quality etc.

Please contact OLED R&D department TRULY Semiconductors LTD. For updated specification and product status before design for this product or release the order.

Dec. 08. 2011

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### Dec. 08. 2011

## **REVISION HISTORY**

Rev.	Contents	Date
0.0	First Release	2011-02-25
0.1	Update ELECTRO-OPTICAL CHARACTERISTICS	
	Update EXTERNAL DIMENSIONS	2011-05-03
	Update OUTGOING QUALITY CONTROL SPECIFICATION	
1.0	Update ELECTRO-OPTICAL CHARACTERISTICS (P.11)	2011-10-21
1.1	Revise INITIALIZATION CODE.(P.18)	2011-12-08
	Revise SCHEMATIC EXAMPLE.(P.21)	

### Rev: 1.1 Dec. 08. 2011

### ■ PHYSICAL DATA

No.	Items:	Specification:	Unit
1	Diagonal Size	2.7	Inch
2	Resolution	256(H) x 64(V)	Dots
3	Active Area	66.53 (W) x 16.61(H)	$mm^2$
4	Outline Dimension (Panel)	82.00 (W) x 25.50(H)	$mm^2$
5	Pixel Pitch	0.26 (W) x 0.26(H)	$mm^2$
6	Pixel Size	0.23 (W) x 0.23 (H)	$mm^2$
7	Driver IC	SSD1322UR1	-
8	Display Color	Yellow	-
9	Grayscale	4	Bit
10	Interface	8-bit 8080/6800 Parallel, SPI	-
11	IC package type	COF with ZIF tail	-
12	Thickness	1.5±0.1	mm
13	Weight	<6.5	g
14	Duty	1/64	-

### ■ ABSOLUTE MAXIMUM RATINGS

Unless otherwise specified,  $V_{SS} = 0V$  (  $Ta = 25^{\circ}C$  )

Items		Symbol	Min	Тур.	Max	Unit
	I/O	$V_{ m DDIO}$	-0.5	1	$V_{CI}$	V
Supply	Logic	$V_{CI}$	-0.3	-	3.6	V
Voltage	Driving	$V_{CC}$	-0.5	-	21.0	V
	Core Logic	$V_{ m DD}$	-0.5	-	2.75	V
Operating '	Operating Temperature		-30	-	80	$^{\circ}\mathbb{C}$
Storage Temperature		Tst	-40	-	85	$^{\circ}\mathbb{C}$
Humidity	Humidity		-	-	90	%RH

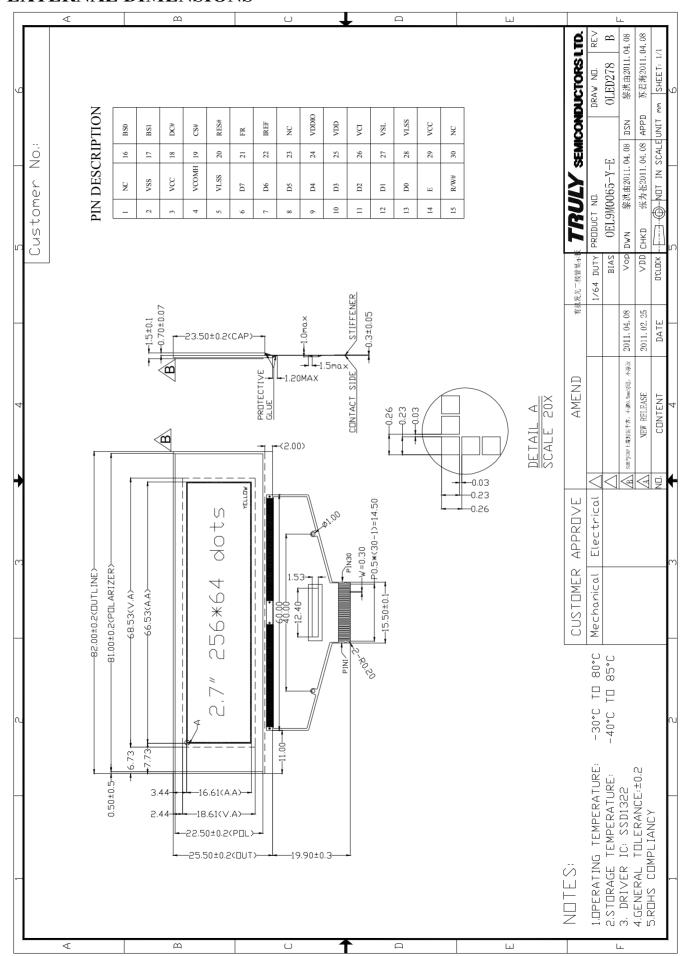
### Note:

Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**Rev: 1.1** 



### **■ EXTERNAL DIMENSIONS**



### ■ ELECTRICAL CHARACTERISTICS

### **◆DC** Characteristics

Unless otherwise specified,  $V_{SS} = 0V$ ,  $V_{CI} = 2.4V$  to 3.5V. (Ta = 25°C)

Items		Symbol	Min	Тур.	Max	Unit
	I/O	$V_{ m DDIO}$	1.65	-	$V_{CI}$	V
Supply	Logic	$V_{CI}$	2.4	3.0	3.5	V
Voltage	Operating	$V_{CC}$	10.0	14.0	20.0	V
	Core Logic	$V_{ m DD}$	2.4	-	2.6	V
Input	High Voltage	$V_{ m IH}$	$0.8 \times V_{DDIO}$	-	$V_{ m DDIO}$	V
Voltage	Low Voltage	$V_{ m IL}$	0	-	$0.2 \text{ x V}_{\text{DDIO}}$	V
Output	High Voltage	$V_{\mathrm{OH}}$	0.9x V <sub>DDIO</sub>	-	$V_{ m DDIO}$	V
Voltage	Low Voltage	$V_{OL}$	0	-	$0.1 \text{ x V}_{\text{DDIO}}$	V

### **◆**AC Characteristics

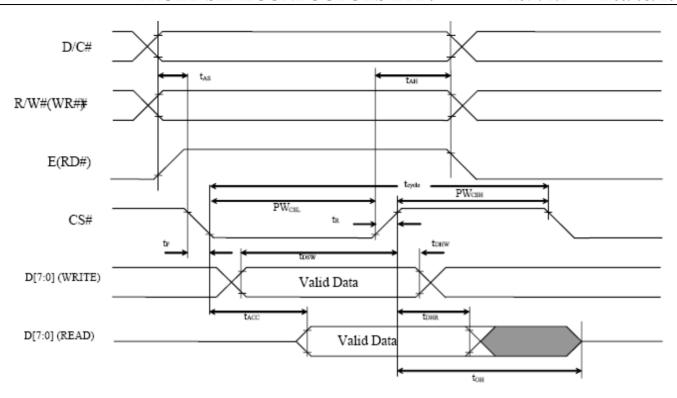
### Use 8080/6800-Series MPU Parallel Interface or Serial Interface

### 1. 6800 Series MPU Parallel Interface

 $(V_{DD} - V_{SS} = 2.4 \text{ to } 2.6 \text{V}, V_{DDIO} = 1.6 \text{V}, V_{CI} = 3.3 \text{V}, T_A = 25^{\circ}\text{C})$ 

Symbol	Parameter	Min	Тур	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	300	-	-	ns
$t_{AS}$	Address Setup Time	10	-	-	ns
$t_{AH}$	Address Hold Time	0	-	-	ns
$t_{DSW}$	Write Data Setup Time	40	-	-	ns
$t_{\mathrm{DHW}}$	Write Data Hold Time	7	-	-	ns
t <sub>DHR</sub>	Read Data Hold Time	20	-	-	ns
t <sub>OH</sub>	Output Disable Time	-	-	70	ns
t <sub>ACC</sub>	Access Time	-	-	140	ns
	Chip Select Low Pulse Width (read)	120			ns
$PW_{CSL}$	Chip Select Low Pulse Width (write)	Low Pulse Width (write) 60			
DW/	Chip Select High Pulse Width (read)	60			*20
$PW_{CSH}$	Chip Select High Pulse Width (write)	60	-	-	ns
$t_R$	Rise Time	-	-	15	ns
t <sub>F</sub>	Fall Time	-	-	15	ns

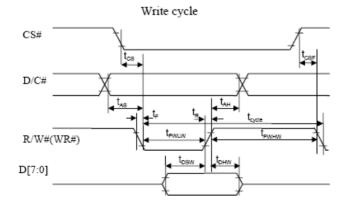


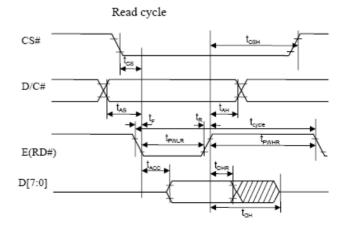


### 2. 8080 Series MPU Parallel Interface

 $(V_{DD} - V_{SS} = 2.4 \text{ to } 2.6 \text{V}, V_{DDIO} = 1.6 \text{V}, V_{CI} = 3.3 \text{V}, T_A = 25 ^{\circ}\text{C})$ 

Symbol	Parameter	Min	Тур	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	300	-	-	ns
t <sub>AS</sub>	Address Setup Time	10	-	-	ns
$t_{AH}$	Address Hold Time	0	-	-	ns
$t_{DSW}$	Write Data Setup Time	40	-	-	ns
$t_{\mathrm{DHW}}$	Write Data Hold Time	7	-	-	ns
t <sub>DHR</sub>	Read Data Hold Time	20	-	-	ns
t <sub>OH</sub>	Output Disable Time	-	-	70	ns
t <sub>ACC</sub>	Access Time	-	-	140	ns
t <sub>PWLR</sub>	Read Low Time		-	-	ns
$t_{PWLW}$	Write Low Time	60	-	-	ns
t <sub>PWHR</sub>	Read High Time	60	-	-	ns
$t_{PWHW}$	Write High Time	60	-	-	ns
$t_R$	Rise Time	-	-	15	ns
$t_{\rm F}$	Fall Time		-	15	ns
t <sub>CS</sub>	Chip select setup time		-	-	ns
t <sub>CSH</sub>	Chip select hold time to read signal	0	-	-	ns
t <sub>CSF</sub>	Chip select hold time	20	-	-	ns

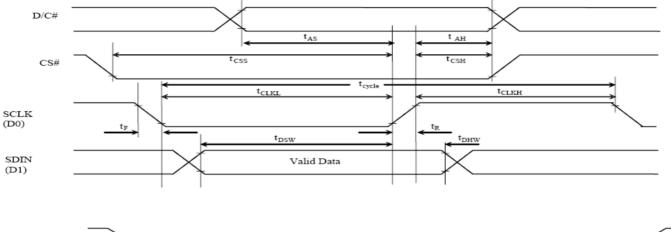


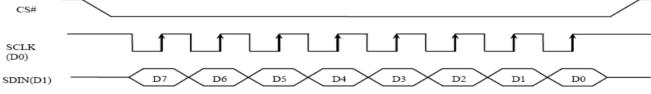


### 3. 4-Wire Serial Interface

 $(V_{\text{DD}}$  -  $V_{\text{SS}}$  = 2.4 to 2.6V,  $V_{\text{DDIO}} \text{=} 1.6\text{V}, \, V_{\text{CI}} \text{=} 3.3\text{V}, \, T_{\text{A}} \text{=} 25^{\circ}\text{C})$ 

Symbol	Parameter	Min	Тур	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	100	-	-	ns
t <sub>AS</sub>	Address Setup Time	15	-	-	ns
t <sub>AH</sub>	Address Hold Time	15	-	-	ns
t <sub>CSS</sub>	Chip Select Setup Time	20	-	-	ns
t <sub>CSH</sub>	Chip Select Hold Time	10	-	-	ns
t <sub>DSW</sub>	Write Data Setup Time	15	-	-	ns
$t_{\mathrm{DHW}}$	Write Data Hold Time	15	-	-	ns
t <sub>CLKL</sub>	Clock Low Time	20	-	-	ns
t <sub>CLKH</sub>	Clock High Time		-	-	ns
t <sub>R</sub>	Rise Time	-	-	15	ns
t <sub>e</sub>	Fall Time	-	_	15	ns

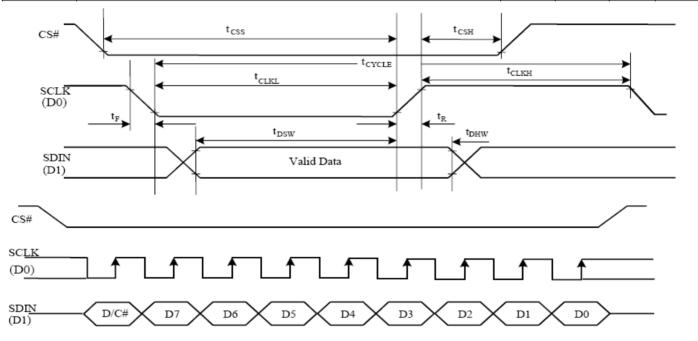




### 4. 3-Wire Serial Interface

 $(V_{\text{DD}}$  -  $V_{\text{SS}}$  = 2.4 to 2.6V,  $V_{\text{DDIO}}\text{=}1.6\text{V},\,V_{\text{CI}}\text{=}3.3\text{V},\,T_{\text{A}}\text{=}25^{\circ}\text{C})$ 

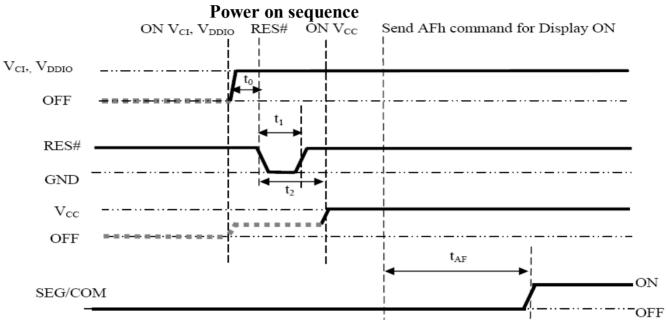
Symbol	Parameter	Min	Тур	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	100	-	-	ns
t <sub>CSS</sub>	Chip Select Setup Time	20	-	-	ns
$t_{CSH}$	Chip Select Hold Time	10	-	-	ns
$t_{DSW}$	Write Data Setup Time	15	-	-	ns
$t_{\mathrm{DHW}}$	Write Data Hold Time	15	-	-	ns
$t_{CLKL}$	Clock Low Time	20	-	-	ns
$t_{CLKH}$	Clock High Time		-	-	ns
$t_R$	Rise Time	-	-	15	ns
$t_{\rm F}$	Fall Time	-	-	15	ns



### 5. TIMING OF POWER SUPPLY

### **◆**Power ON sequence:

- 1. Power ON V<sub>CI</sub>, V<sub>DDIO</sub>.
- 2. After  $V_{CI}$ ,  $V_{DDIO}$  becomes stable, set wait time at least 1ms ( $t_0$ ) for internal  $V_{DD}$  become stable. Then set RES# pin LOW (logic low) for at least 100us ( $t_1$ ) <sup>(4)</sup> and then HIGH (logic high).
- 3. After set RES# pin LOW (logic low), wait for at least 100us (t<sub>2</sub>). Then Power ON V<sub>CC</sub>. (1)
- 4. After  $V_{CC}$  become stable, send command AFh for display ON. SEG/COM will be ON after  $200 ms(t_{AF})$ .



### ◆ Power OFF sequence:

- 1. Send command AEh for display OFF.
- 2. Power OFF V<sub>CC</sub>. (1), (2), (3)
- 3. Wait for  $t_{OFF}$ . Power OFF  $V_{Cl_1}$   $V_{DDIO}$ . (where Minimum  $t_{OFF}$ =0ms (5), Typical  $t_{OFF}$ =100ms)

# Send command AEh for display OFF OFF V<sub>CC</sub> OFF V<sub>CI</sub>, V<sub>DDIO</sub> V<sub>CC</sub> OFF V<sub>CI</sub>, V<sub>DDIO</sub> OFF

### Note:

- <sup>(1)</sup> Since an ESD protection circuit is connected between  $V_{CI}$ ,  $V_{DDIO}$  and  $V_{CC}$ ,  $V_{CC}$  becomes lower than  $V_{CI}$  whenever  $V_{CI}$ ,  $V_{DDIO}$  is ON and  $V_{CC}$  is OFF as shown in the dotted line of  $V_{CC}$  in Figure above.
- <sup>(2)</sup>V<sub>CC</sub> should be kept float (disable) when it is OFF.
- (3) Power pins (V<sub>CI</sub>, V<sub>CC</sub>) can never be pulled to ground under any circumstance.
- $^{(4)}$  The register values are reset after  $t_1$ .
- (5) VCI, V<sub>DDIO</sub> should not be Power OFF before VCC Power OFF.



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### **■ ELECTRO-OPTICAL CHARACTERISTICS (Ta=25°C)**

Items		Symbol	Min.	Тур.	Max.	Unit	Remark
Operating Lumi	nance	L	80	100*	-	cd /m <sup>2</sup>	Yellow
Power Consum	ntion	P		155	165	mW	30% pixels ON
Power Consum	риоп	Γ	-	133	103	IIIW	$L=100cd/m^2$
Frame Freque	Frame Frequency		-	100	-	Hz	-
Color Coordinate	Yellow	CIE x	0.42	0.46	0.50	CIE1931	Darkroom
Color Coordinate	1 chow	CIE y	0.47	0.51	0.55	CIE1931	Darkiooni
Pagnanga Tima	Rise	Tr	-	-	0.02	ms	-
Response Time	Decay	Td	-	-	0.02	ms	-
Contrast Ratio*		Cr	10000:1	-	1	-	Darkroom
Viewing Angle Uniformity		Δ θ	160	-	-	Degree	-
Operating Life	Гіте*	Тор	40,000	-	-	Hours	$L=100cd/m^2$

### Note:

- 1.  $100cd/m^2$  is based on  $V_{CI}=3.0V$ ,  $V_{CC}=14.0V$ , contrast command setting 0x5F;
- 2. Contrast ratio is defined as follows:

3. Life Time is defined when the Luminance has decayed to less than 50% of the initial Luminance specification. (Odd and even chess board alternately displayed) (The initial value should be closed to the typical value after adjusting.)

## ■ INTERFACE PIN CONNECTIONS

No	Symbol	Description			
1	NC	No connection			
2	VSS	Ground. Common Voltage Reference Pin			
3	VCC	Power supply for panel driving voltage. Segment voltage			
4	VCOMH	COM signal deselected voltage level. High Level Voltage Output Of COM Signal			
5	VLSS	Analog system ground pin. Voltage Supply			
6-13	D7-D0	These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW. (Except for D2 pin in SPI mode, D2 is pulled low in SPI mode).			
14	E (RD#)	MCU Interface Input pin, in 6800 parallel mode, it is used as enable signal, read/write operation is initiated when this pin is set high with chip selected. In 8080 parallel mode, this pin receives read signal, read operation is initiated when this is pulled low with chip selected. When SPI interface is selected, this pin must be connected to ground.			
15	R/W#(WR#)	MCU Interface Input pin, in 6800 parallel mode, it is used as read/write selection input, read mode will be carried out when This pin is pulled high while write mode with this pin pulled low. In 8080 parallel mode, this pin will be write input, write operation is initiated when this is pulled low with chip selected. When SPI interface is selected, this pin must be connected to ground.			
16- 17	BS0-1	MCU bus interface selection pins. Select appropriate logic setting as described in the following table.    BS[1:0]   Bus Interface Selection			
18	D/C#	This pin is Data/Command control pin connected to the MCU. When the pin is pulled HIGH, the content at D[7:0] will be interpreted as data. When the pin is pulled LOW, the content at D[7:0] will be interpreted as command.			
19	CS#	This pin is the chip select input connected to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW.			
20	RES#	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin pull HIGH during normal operation.			

21	FR	This pin is No Connection pins. Nothing should be connected to this pin. This pin should be left open individually.
22	IREF	This pin is the segment output current reference pin. A resistor should be connected between this pin and VSS to maintain the current around 10uA.
23	NC	No connection.
24	VDDIO	Power supply for interface logic level. It should be matched with the MCU interface voltage level.
25	VDD	Power supply pin for core logic operation. A capacitor is required to connect between this pin and VSS.
26	VCI	Low voltage power supply. VCI must always be equal to or higher than VDD and VDDIO.
27	VSL	This is segment voltage reference pin. When external VSL is used, connect with resistor and diode to ground
28	VLSS	Analog system ground pin.
29	VCC	Power supply for panel driving voltage. Segment Voltage
30	NC	No Connection.



### **■ COMMAND TABLE**

<b>D</b> / <b>C</b> #	Hex	<b>D</b> 7	D6	<b>D</b> 5	D4	D3	D2	D2	D0	Command	Description
0	00	0	0	0	0	0	0	0	0	Enable Gray Scale table	This command is sent to enable the Gray Scale table setting (command B8h)
0 1 1	15 A[6:0] B[6:0]	0 *	0 A <sub>6</sub> B <sub>6</sub>	0 A <sub>5</sub> B <sub>5</sub>	1 A <sub>4</sub> B <sub>4</sub>	0 A <sub>3</sub> B <sub>3</sub>	1 A <sub>2</sub> B <sub>2</sub>	0 A <sub>1</sub> B <sub>1</sub>	1 A <sub>0</sub> B <sub>0</sub>	Set Column Address	Set Column start and end address A[6:0]: Start Address. [reset=0] B[6:0]: End Address. [reset=119] Range from 0 to 119
0	5C	0	1	0	1	1	1	0	0	Write RAM Command	Enable MCU to write Data into RAM
0	5D	0	1	0	1	1	1	0	1	Read RAM Command	Enable MCU to read Data from RAM
0 1 1	75 A[6:0] B[6:0]	0 *	1 A <sub>6</sub> B <sub>6</sub>	1 A <sub>5</sub> B <sub>5</sub>	1 A <sub>4</sub> B <sub>4</sub>	0 A <sub>3</sub> B <sub>3</sub>	1 A <sub>2</sub> B <sub>2</sub>	0 A <sub>1</sub> B <sub>1</sub>	1 A <sub>0</sub> B <sub>0</sub>		Set Row start and end address A[6:0]: Start Address. [reset=0] B[6:0]: End Address. [reset=127] Range from 0 to 127
0 1 1	A0 A[7:0] B[4]	1 0 *	0 0 *	1 A <sub>5</sub> 0	0 A <sub>4</sub> B <sub>4</sub>	0 0 0	0 A <sub>2</sub> 0	0 A <sub>1</sub> 0	0 A <sub>0</sub> 1	Set Re-map and Dual COM Line mode	
0	A1 A[6:0]	1 *	0 A <sub>6</sub>	1 A <sub>5</sub>	0 A <sub>4</sub>	0 A <sub>3</sub>	0 A <sub>2</sub>	0 A <sub>1</sub>	1 A <sub>0</sub>	Set Display Start Line	Set display RAM display start line register from 0-127 Display start line register is reset to 00h after RESET

<b>D</b> / <b>C</b> #	Hex	<b>D</b> 7	D6	<b>D</b> 5	D4	D3	D2	D2	<b>D</b> 0	Command	Description		
0	A2	1	0	1	0	0	0	1	0		·		
1	A[6:0]	*	$A_6$	$A_5$	$A_4$	$A_3$	$A_2$	$A_1$	$A_0$	Set Display Offset	Set vertical scroll by COM from 0-127 The value is reset to 00H after RESET		
										Oliset	The value is reset to our after KESE1		
0	A4~A7	1	0	1	0	0	$X_2$	$X_l$	$X_0$		A4h = Entire Display OFF, all pixels turns OFF in GS level 0		
											A5h = Entire Display ON, all pixels turns ON in GS level 15		
										Set Display Mode	A6h = Normal Display [reset]		
										1,1000	A7h = Inverse Display (GS0 → GS15, GS1 → GS14, GS2		
											→ GS13,)		
0	A8	1	0	1	0	1	0	0	0		This command turns ON partial mode. The partial mode		
1	A[6:0]	0	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	Aı	A <sub>0</sub>	Enable Partial	display area is defined by the following two parameters,		
1	B[6:0]	0	$B_6$	B <sub>5</sub>	$B_4$	$B_3$	$B_2$	$B_1$	$B_0$	Display	A[6:0]: Address of start row in the display area		
											B[6:0]: Address of end row in the display area, where B[6:0] must be ≥ A[6:0]		
0	A9	1	0	1	0	1	0	0	1	Exit Partial	This command is sent to exit the Partial Display mode		
										Display			
0	AB A[0]	1 0	0	0	0	1 0	0	1	1 A <sub>0</sub>	Function	A[0]=0b, Select external V <sub>DD</sub>		
1	Α[0]	0	U	0	0	0	0	U	A <sub>0</sub>	Selection	A[0]=1b, Enable internal V <sub>DD</sub> regulator [reset]		
0	AE~AF	1	0	1	0	1	1	1	$X_0$	Cat Class made	A.F.h Clean made ON (Display OFF)		
										ON/OFF	AEh = Sleep mode ON (Display OFF) AFh = Sleep mode OFF (Display ON)		
0	B1 A[7:0]	1 A <sub>7</sub>	0 A <sub>6</sub>	1 A <sub>5</sub>	1 A <sub>4</sub>	0 A <sub>3</sub>	0 A <sub>2</sub>	0 A <sub>1</sub>	1 A <sub>0</sub>		A[3:0] Phase 1 period (reset phase length) of 5~31 DCLK(s) clocks as follow:		
1	A[7.0]	A.7	A6	A.5	A.4	A.3	A.2	Al	A <sub>0</sub>				
											A[3:0] Phase 1 period 0000 invalid		
											0001 invalid		
											0010 5 DCLKs		
											0011 7 DCLKs		
											0100 9 DCLKs [reset]		
											1111 31 DCLKs		
											IIII SI DELKS		
										Set Phase	AF7 41 P1 - 0 - 1 1/6 4 - 1 - 1 - 1 - 1 - 1 - 6		
										Length	A[7:4] Phase 2 period (first pre-charge phase length) of 3~15 DCLK(s) clocks as follow:		
											A[7:4] Phase 2 period		
											0000 invalid		
											0001 invalid		
											0010 invalid		
											0011 3 DCLKs		
											: : : 0111 7 DCLKs [reset]		
											0111 7 DCLKs [reset]		
											1111 15 DCLKs		

<b>D</b> / <b>C</b> #	Hex	<b>D</b> 7	D6	<b>D</b> 5	D4	D3	D2	D2	<b>D</b> 0	Command	Description
0	В3	1	0	1	1	0	0	1	1		A[3:0] [reset=0], divide by DIVSET where
	A [7:0]	_		_	_	_	,		_		
1	A[7:0]	$A_7$	$A_6$	$A_5$	$A_4$	$A_3$	$A_2$	$A_1$	$A_0$		A[3:0] DIVSET
											0000 divide by 1
											0001 divide by 2
											0010 divide by 4
											0011 divide by 8
											0100 divide by 16
											0101 divide by 32
										Set Front Clock	0110 divide by 64
										Divider /	0111 divide by 128
										Oscillator	1000 divide by 256
										Frequency	1001 divide by 512
											1010 divide by 1024
											>=1011 invalid
											A[7:4] Oscillator frequency, frequency increases as level increases [reset=0101b]
0	B4	1	0	1	1	0	1	0	0		A[1:0] = 00b: Enable external VSL
-		-	_	-	-	-					A[1:0] = 10b: Internal VSL [reset]
1	A[1:0]	1	0	1	0	0	0	$A_1$	$A_0$		
1	B[7:3]	$B_7$	$B_6$	$B_5$	$B_4$	$B_3$	1	0	1		
										Display Enhancement A	B[7:3] = 11111b: Enhanced low GS display quality B[7:3] = 10110b: Normal [reset]
0	B5	1	0	1	1	0	1	0	1		A[1:0] GPIO0: 00 pin HiZ, Input disabled
-		1	_	-	_	~	_		-		01 pin HiZ, Input enabled
1	A[3:0]	*	*	*	*	A <sub>3</sub>	$A_2$	$A_1$	$A_0$		10 pin output LOW [reset] 11 pin output HIGH
										Set GPIO	A[3:2] GPIO1: 00 pin HiZ, Input disabled 01 pin HiZ, Input enabled 10 pin output LOW [reset] 11 pin output HIGH
	D.c	1	0	1	1	0	1	1	0		A[3:0] Second Pre-charge period
0	B6	1	0	1	1	0	1	1	0		0000b 0 dclk
1	A[3:0]	*	*	*	*	$A_3$	$A_2$	$A_1$	$A_0$		0001b 1 dclk
										Set Second Precharge Period	1000b 8 dclks [reset]  1111b 15 dclks



<b>D</b> / <b>C</b> #	Hex	<b>D</b> 7	D6	<b>D</b> 5	D4	D3	D2	D2	<b>D</b> 0	Command	Description	
0	B8	1	0	1	1	1	0	0	0		The next 15 data bytes define Gray Scale (GS) Table by	
1	A1[7:0]	A1 <sub>7</sub>	A16	A15	A14	A1 <sub>3</sub>	A12	$A1_1$	A10		setting the gray scale pulse width in unit of DCLK's	
1	A2[7:0]		A26	A25	A24	A2 <sub>3</sub>	A22	A2 <sub>1</sub>	A20		(ranges from 0d ~ 180d)	
1										Set Gray Scale	A1[7:0]: Gamma Setting for GS1,	
1										Table	A1[7:0]: Gamma Setting for GS1, A2[7:0]: Gamma Setting for GS2,	
1											:	
1	A14[7:0]	A147	A146	A145	A144	A143	A142	A14 <sub>1</sub>	A14 <sub>0</sub>		A14[7:0]: Gamma Setting for GS14,	
1	A15[7:0]	A157	A156	A155	A154	A15 <sub>3</sub>	A152	A15 <sub>1</sub>	A15 <sub>0</sub>		A15[7:0]: Gamma Setting for GS15	
											Note  (1) 0 ≤ Setting of GS1 < Setting of GS2 < Setting of GS3  < Setting of GS14 < Setting of GS15  Refer to Section 8.8 for details  (2) The setting must be followed by the Enable Gray Scale Table command (00h)	
0	В9	1	0	1	1	1	0	0	1		The default Linear Gray Scale table is set in unit of DCLK's as follow	
										Select Default Linear Gray Scale table	GS0 level pulse width = 0; GS1 level pulse width = 0; GS2 level pulse width = 8; GS3 level pulse width = 16; : : : : : : : : : : : : : : : : : : :	
0	BB	1	0	1	1	1	0	1	1		Set pre-charge voltage level.[reset = 17h]	
1	A[4:0]	*	*	*	$A_4$	$A_3$	$A_2$	$A_1$	$A_0$			
											A[4:0] Hex code pre-charge voltage	
										Set Pre-charge	00000 00h 0.20 x V <sub>CC</sub>	
										voltage	: : : :   :	
0	BE	1	0	1	1	1	1	1	0		Set COM deselect voltage level [reset = 04h]	
1	A[2:0]	*	*	*	*	0	$A_2$	$A_1$	$A_0$			
											A[2:0] Hex code V <sub>COMH</sub>	
										Set V <sub>COMH</sub>	000 00h 0.72 x V <sub>CC</sub>	
										See TOME	100 04h 0.80 x V <sub>CC</sub> [reset]	
											: : : : 111 07h 0.86 x V <sub>CC</sub>	
0	C1	1	1	0	0	0	0	0	1	Set Contrast	A[7:0]: Contrast current value, range:00h~FFh,	
1	A[7:0]	$A_7$	$A_6$	$A_5$	$A_4$	$A_3$	$A_2$	$A_1$	$A_0$	Current	i.e. 256 steps for I <sub>SEG</sub> current [reset = 7Fh]	
L												

<b>D</b> / <b>C</b> #	Hex	<b>D</b> 7	<b>D</b> 6	<b>D</b> 5	D4	D3	D2	D2	$\mathbf{D}0$	Command	Description
0	C7	1	1	0	0	0	1	1	1		A[3:0] =
1	A[3:0]	*	*	*	*	Αą	$A_2$	$A_1$	$A_0$		0000b, reduce output currents for all colors to 1/16
	[]					,		1	0	Master Contrast	0001b, reduce output currents for all colors to 2/16
										Current Control	: 1110b, reduce output currents for all colors to 15/16
											1111b, no change [reset]
											11110, no change [reset]
0	CA	1	1	0	0	1	0	1	0		A[6:0]: Set MUX ratio from 16MUX ~ 128MUX
1	A[6:0]	*	$A_6$	$A_5$	$A_4$	$A_3$	$A_2$	$A_1$	$A_0$		A[G:0] = 15d concessor 16MIV
										Set MUX Ratio	A[6:0] = 15d represents 16MUX
											A[6:0] = 127d represents 128MUX [reset]
0	D1	1	1	0	1	0	0	0	1		
1	A[5:4]	1	0	$A_5$	$A_4$	0	0	1	0		A[5:4] = 00b: Reserved
1	20	0	0	1	0	0	0	0	0	Enhancement B	A[5:4] = 10b: Normal [reset]
0	FD	1	1	1	1	1	1	0	1		A[2]: MCU protection status [reset = 12h]
1	A[2]	0	0	0	1	0	$A_2$	1	0		Afol of the company of the
											A[2] = 0b, Unlock OLED driver IC MCU interface from
										Set Command	entering command [reset] A[2] = 1b, Lock OLED driver IC MCU interface from
										Lock	entering command
											Note
											(1) The locked OLED driver IC MCU interface prohibits all
											commands and memory access except the FDh command

### ■ INITIALIZATION CODE

```
void Inital_SSD1322()
/* Command lock setting */
 WMLCDCOM(0xFD);
 WMLCDDATA(0x12);
 /* Display OFF*/
 WMLCDCOM(0xAE);
 /* Column address setting */
 WMLCDCOM(0x15);
 WMLCDDATA(0x1C);
 WMLCDDATA(0x5B);
 /* Row address setting */
 WMLCDCOM(0x75);
 WMLCDDATA(0x00);
 WMLCDDATA(0x3F);
/* Re-map& Dual Com mode */
WMLCDCOM(0xA0);
 WMLCDDATA(0x14);
 WMLCDDATA(0x11); //Enable dual com mode
```



```
/* Display start line */
WMLCDCOM(0xA1);
WMLCDDATA(0x00);
/* Display offset */
WMLCDCOM(0xA2);
WMLCDDATA(0x00);
/* Normal display */
WMLCDCOM(0xA6);
 /* Partial display setting */
//WMLCDCOM(0xA8);
//WMLCDDATA(0x00); //Start row
//WMLCDDATA(0x3F); //End row
//WMLCDCOM(0xA9); //Exit partial display mode
/* Function selection*/
WMLCDCOM(0xAB);
WMLCDDATA(0x01); //A[0]=1b, Enable internal VDD; A[0]=0b, Select external VDD
/* Phase length setting */
WMLCDCOM(0xB1);
WMLCDDATA(0x74); //Phase1=9dclk, Phase2=7dclk
/* Set Front Clock Divider /Oscillator Frequency */
WMLCDCOM(0xB3);
WMLCDDATA(0x91);
/* Display enhancement A */
WMLCDCOM(0xB4);
WMLCDDATA(0xA0); // Enable external VSL
WMLCDDATA(0xB5); // Normal [reset]
/* GPIO setting */
//WMLCDCOM(0xB5):
//WMLCDDATA(0x0A);
/* Second precharge period setting */
WMLCDCOM(0xB6);
WMLCDDATA(0x08);
/* Set precharge voltage */
WMLCDCOM(0xBB);
WMLCDDATA(0x17);
/* Set VCOMH voltage */
WMLCDCOM(0xBE);
WMLCDDATA(0x04); //0.80*VCC
```

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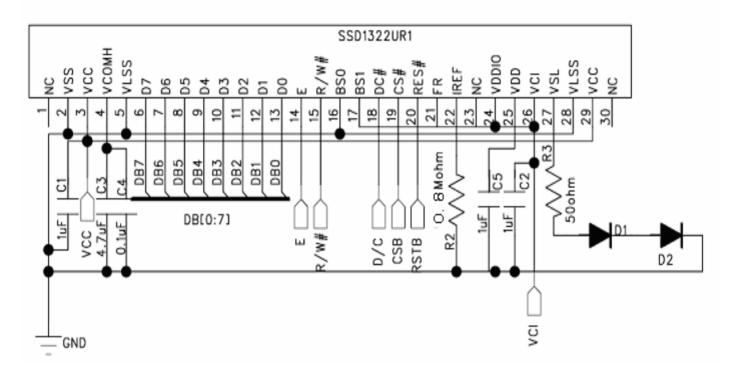
```
/* Contrast setting */
WMLCDCOM(0xC1);
WMLCDDATA(CONTRAST);
/* Master current set */
WMLCDCOM(0xC7);
WMLCDDATA(0x0F);
/* Set multiplex ratio */
WMLCDCOM(0xCA):
WMLCDDATA(0x3F);
/* Display enhancement B */
WMLCDCOM(0xD1);
WMLCDDATA(0xA2); // Normal [reset]
WMLCDDATA(0x20);
/* Select default linear gray scale table */
WMLCDCOM (0XB9);
WMLCDCOM(0x00); //Enable gray scale setting
WMLCDCOM(0xB8); //Gray scale setting
WMLCDDATA(0x00); //GS1=0
WMLCDDATA(0x0C); //GS2=12
WMLCDDATA(0x18); //GS3=24
WMLCDDATA(0x24); //GS4=36
WMLCDDATA(0x30); //GS5=48
WMLCDDATA(0x3C); //GS6=60
WMLCDDATA(0x48); //GS7=72
WMLCDDATA(0x54); //GS8=84
WMLCDDATA(0x60); //GS9=96
WMLCDDATA(0x6C); //GS10=108
WMLCDDATA(0x78); //GS11=120
WMLCDDATA(0x84); //GS12=132
WMLCDDATA(0x90); //GS13=144
WMLCDDATA(0x9C); //GS14=156
WMLCDDATA(0xA8); //GS15=168
*/
/* Display ON */
WMLCDCOM(0xAF);
```

### Note:

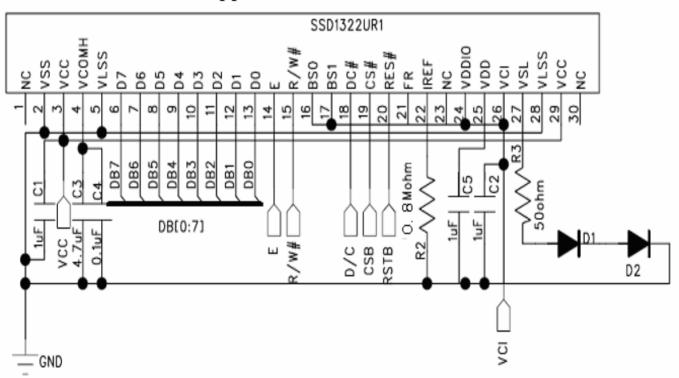
Please set appropriate parameters of initialization base on actual application.

### ■ SCHEMATIC EXAMPLE

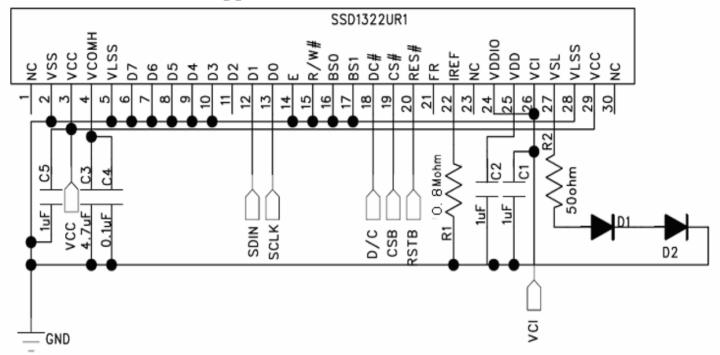
### **♦8080** Series Interface Application Circuit:



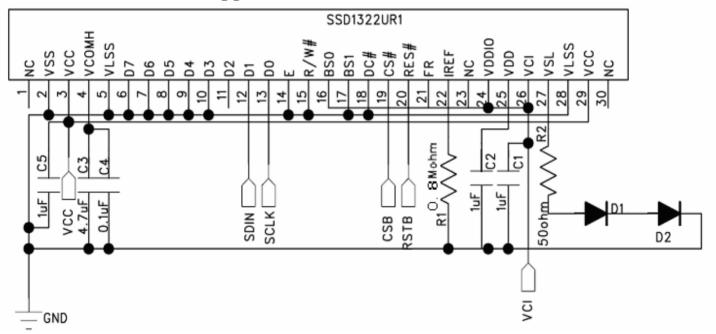
### **♦6800** Series Interface Application Circuit:



### **◆**4-wire SPI Interface Application Circuit:



### **◆3**-wire SPI Interface Application Circuit:



For Above Circuits:

Voltage at IREF = VCC - 6V. For VCC = 14.0V, VCI=3.0V, IREF = 10uA;

R1 = (Voltage at IREF - VSS) / IREF=  $(14 - 6) / 10uA = 0.8 M\Omega$ .

 $R2 = 50 \Omega, 1/8W$ 

D1&D2: Vth = 0.7V, 1N4148

 $C1 \sim C2$ , C3, C5:  $4.7 uF^{(1)}$ 

C4:  $0.1uF^{(2)}$ 

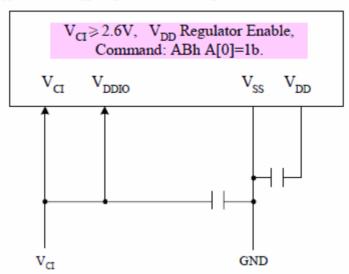
 $^{(1)}$  (2) The value of components is recommended value. Select appropriate value against module application.

### Note:

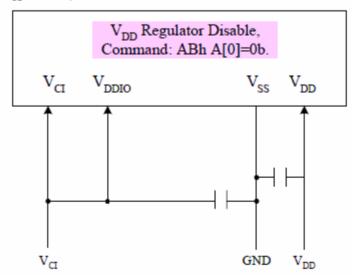
In SSD1322, the power supply pin for core logic operation, VDD, can be supplied by external source or internally regulated through the VDD regulator. The internal VDD regulator is enabled by setting bit A[0] to 1b in command ABh "Function Selection". VCI should be larger than 2.6V when using the internal VDD regulator. The typical regulated VDD is about 2.5V It should be notice that, no matter VDD is supplied by external source or internally regulated; VCI must always be set equivalent to or higher than VDD and VDDIO.

The following figure shows the VDD regulator pin connection scheme:

 $V_{CI} > 2.6V$ ,  $V_{DD}$  regulator enable pin connection scheme



 $V_{CI} < 2.6V, V_{DD}$  regulator disable pin connection scheme



### ■ RELIABILITY TESTS

	Item	Condition	Criterion				
High Te	emperature Storage (HTS)	85±2°C, 200 hours	<ol> <li>After testing, the function test is ok.</li> <li>After testing, no addition to the defect.</li> </ol>				
High Ter	mperature Operating (HTO)	80±2°C, 96 hours	3. After testing, the change of luminance should be within +/- 50% of initial value.				
Low Te	emperature Storage (LTS)	-40±2°C, 200 hours	4. After testing, the change for the mono and area color must be within (+/-0.02, +/-				
Low Ter	mperature Operating (LTO)	-30±2°€, 96 hours	0.02) and for the full color it must be within (+/-0.04, +/-0.04) of				
High Tempe	erature / High Humidity Storage (HTHHS)	50±3°C, 90%±3%RH, 120 hours	initial value based on 1931 CIE coordinates. 5. After testing, the change of total current				
Thermal S	hock (Non-operation) (TS)	-20±2°C ~ 25°C ~ 70±2°C (30min) (5min) (30min) 10cycles	consumption should be within +/- 50% of initial value.				
Vibration (Packing)	10~55~10Hz,amplitu de 1.5mm, 1 hour for each direction x, y, z	1. One box for each test.	e and the electrical defects.				
Drop (Packing)	Height: 1 m, each time for 6 sides, 3 edges, 1 angle	2. INO addition to the cosmetic					
ESD (finished product housing)	±4kV (R: 330Ω C: 150pF , 10times, air discharge)	<ol> <li>After testing, cosmetic and electrical defects should not happen.</li> <li>In case of malfunction or defect caused by ESD damage, it would be judged as a good part if it would be recovered to normal state after resetting.</li> </ol>					

Note: 1) For each reliability test, the sample quantity is 3, and only for one test item.

- 2) The HTHHS test is requested the Pure Water(Resistance>10M $\Omega$ ).
- 3) The test should be done after 2 hours of recovery time in normal environment.

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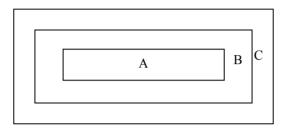
### ■ OUTGOING QUALITY CONTROL SPECIFICATION

### **♦**Standard

According to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, General Inspection Level II.

### **♦** Definition

- 1 Major defect: The defect that greatly affect the usability of product.
- 2 Minor defect: The other defects, such as cosmetic defects, etc.
- 3 Definition of inspection zone:



Zone A: Active Area

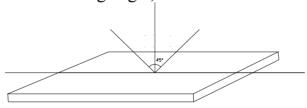
Zone B: Viewing Area except Zone A

Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer's product.

### **◆Inspection Methods**

1 The general inspection: under 20W x 2 or 40W fluorescent light, about 30cm viewing distance, within 45° viewing angle, under 25±5°C.



2 The luminance and color coordinate inspection : By PR705 or BM-7 or the equal equipments, in the dark room, under  $25\pm5$  °C.

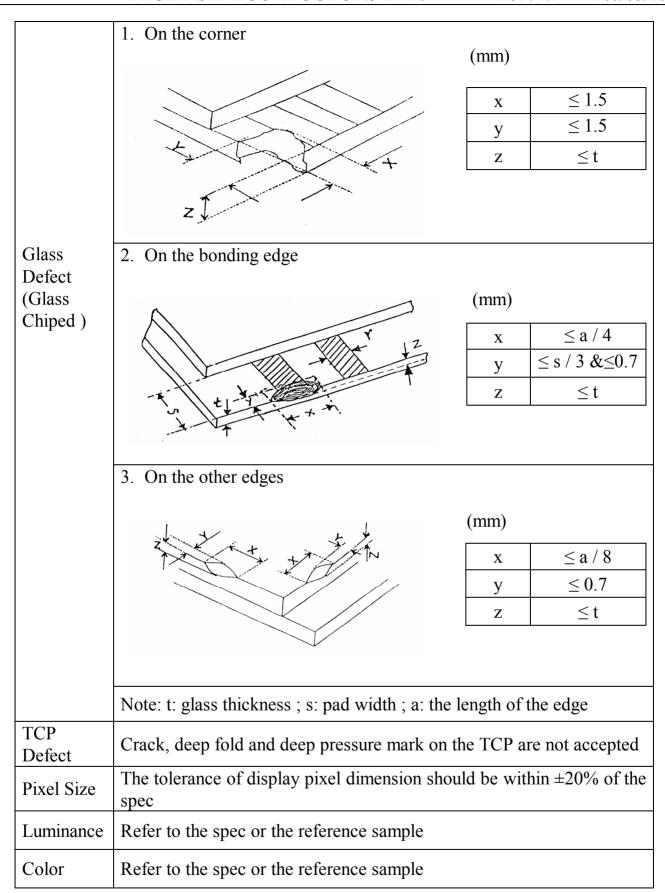
### **◆Inspection Criteria**

1 Major defect : AQL= 0.65

ujor delect : 11 2 2 0.05								
Item	Criterion							
	1. No display or abnormal display is not accepted							
Function Defect	2. Open or short is not accepted.							
	3. Power consumption exceeding the spec is not accepted.							
Outline Dimension	Outline dimension exceeding the spec is not accepted.							
Glass Crack	Glass crack tends to enlarge is not accepted.							

### 2 Minor Defect : AQL= 1.5

Item	: AQL= 1.5	Criterion								
	Size		Accepted Q	ty						
Spot			Area A + Area B	Area C						
Defect		Φ≦0.07	Ignored							
(dimming and	$  ( \mathbf{Y} )  $	$0.07 < \Phi \le 0.10$	3							
lighting	X	0.10<Φ≦0.15	1	Ignored						
spot)	<del> </del>	0.15<Φ	0							
	Note: $\Phi = (x + y) /$	2	l							
Line	L ( Length ): mm	W ( Width ): mm	Area A + Area B	Area C						
Defect	/	$W \leq 0.02$	Ignored							
(dimming and	L≦3.0	$0.02 < W \le 0.03$	2							
lighting	L≦2.0	$0.03 < W \le 0.05$	1	Ignored						
line)	/	0.05 <w< td=""><td>As spot defect</td><td colspan="3"></td></w<>	As spot defect							
Polarizer Stain	Stain which can be wiped off lightly with a soft cloth or similar cleaning is accepted, otherwise, according to the Spot Defect and the Line Defect.									
		een during operation,  nd the Line Defect.	according to the cri	terions						
		een only under non-o	peration or some spe	ecial						
Polarizer	L ( Length ): mm	W ( Width ): mm	Area A + Area B	Area C						
Scratch	/	W ≤ 0.02	Ignore							
	3.0 <l≦5.0< td=""><td><math>0.02 &lt; W \le 0.04</math></td><td>2</td><td></td></l≦5.0<>	$0.02 < W \le 0.04$	2							
	L≦3.0	$0.04 < W \le 0.06$	1	Ignore						
	/	0.06 <w< td=""><td>0</td><td></td></w<>	0							
	Si	ze	Area A + Area B	Area C						
Polarizer		$\Phi \leq 0.20$	Ignored							
Air Bubble	Y	$0.20 < \Phi \leq 0.30$	2	_						
20010	X	$0.30 < \Phi \leq 0.50$	1	Ignored						
		0.50<Φ	0							



### ■ CAUTIONS IN USING OLED MODULE

### **◆**Precautions For Handling OLED Module:

1. OLED module consists of glass and polarizer. Pay attention to the following items when handling:

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- i. Avoid drop from high, avoid excessive impact and pressure.
- ii. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead.
- iii. If the surface becomes dirty, breathe on the surface and gently wipe it off with a soft dry cloth. If it is terrible dirty, moisten the soft cloth with Isopropyl alcohol or Ethyl alcohol. Other solvents may damage the polarizer. Especially water, Ketone and Aromatic solvents.
- iv. Wipe off saliva or water drops immediately, contact the polarizer with water over a long period of time may cause deformation.
- v. Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peeling-off may occur with high temperature and high humidity.
- vi. Condensation on the surface and the terminals due to cold or anything will damage, stain or dirty the polarizer, so make it clean as the way of iii.
- 2. Do not attempt to disassemble or process the OLED Module.
- 3. Make sure the TCP or the FPC of the Module is free of twisting, warping and distortion, do not pull or bend them forcefully, especially the soldering pins. On the other side, the SLIT part of the TCP is made to bend in the necessary case.
- 4. When assembling the module into other equipment, give the glass enough space to avoid excessive pressure on the glass, especially the glass cover which is much more fragile.
- 5. Be sure to keep the air pressure under 120 kPa, otherwise the glass cover is to be cracked.
- 6. Be careful to prevent damage by static electricity:
  - i. Be sure to ground the body when handling the OLED Modules.
  - ii. All machines and tools required for assembling, such as soldering irons, must be properly grounded.
  - iii. Do not assemble and do no other work under dry conditions to reduce the amount of static electricity generated. A relative humidity of 50%-60% is recommended.
  - iv. Peel off the protective film slowly to avoid the amount of static electricity generated.
  - v. Avoid to touch the circuit, the soldering pins and the IC on the Module by the body.
  - vi. Be sure to use anti-static package.
- 7. Contamination on terminals can cause an electrochemical reaction and corrade the terminal circuit, so make it clean anytime.
- 8. All terminals should be open, do not attach any conductor or semiconductor on the terminals.
- 9. When the logic circuit power is off, do not apply the input signals.
- 10. Power on sequence:  $V_{DD} \rightarrow V_{CC}$ , and power off sequence:  $V_{CC} \rightarrow V_{DD}$ .
- 11. Be sure to keep temperature, humidity and voltage within the ranges of the spec, otherwise shorten Module's life time, even make it damaged.
- 12. Be sure to drive the OLED Module following the Specification and datasheet of IC controller, otherwise something wrong may be seen.

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13. When displaying images, keep them rolling, and avoid one fixed image displaying more than 30 seconds, otherwise the residue image is to be seen. This is the speciality of OLED.

### **◆**Precautions For Soldering OLED Module:

- 1. Soldering temperature :  $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$ .
- 2. Soldering time: 3-4 sec.
- 3. Repeating time: no more than 3 times.
- 4. If soldering flux is used, be sure to remove any remaining flux after finishing soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended to protect the surface with a cover during soldering to prevent any damage due to flux spatters.

### **◆** Precautions For Storing OLED Module:

- 1. Be sure to store the OLED Module in the vacuum bag with dessicant.
- 2. If the Module can not be used up in 1 month after the bag being opened, make sure to seal the Module in the vacuum bag with dessicant again.
- 3. Store the Module in a dark place, do not expose to sunlight or fluorescent light.
- 4. The polarizer surface should not touch any other objects. It is recommended to store the Module in the shipping container.
- 5. It is recommended to keep the temperature between 0°C and 30°C, the relative humidity not over 60%.

### **♦** Limited Warranty

Unless relevant quality agreements signed with customer and law enforcement, for a period of 12 months from date of production, all products (except automotive products) TRULY will replace or repair any of its OLED modules which are found to be functional defect when inspected in accordance with TRULY OLED acceptance standards (copies available upon request). Cosmetic/visual defects must be returned to TRULY within 90 days of shipment. Confirmation of such date should be based on freight documents. The warranty liability of TRULY is limited to repair and/or replacement on the terms above. TRULY will not be responsible for any subsequent or consequential events.

### **◆Return OLED Module Under Warranty:**

- 1. No warranty in the case that the precautions are disregarded.
- 2. Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects.

### **♦PRIOR CONSULT MATTER**

- 1. For TRULY standard products, we keep the right to change material ,process ... for improving the product property without any notice on our customer.
- 2. If you have special requirement about reliability condition, please let us know before you start the test on our samples.